

IGBT Modules

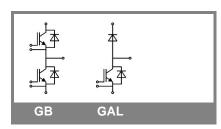
SKM 150GB123D SKM 150GAL123D

Features

- MOS input (voltage controlled)
- N channel, Homogeneous Si
- · Low inductance case
- Very low tail current with low temperature dependence
- High short circuit capability, self limiting to 6 x I_{cnom}
- · Latch-up free
- Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding
- Large clearance (12 mm) and creepage distances (20 mm)

Typical Applications

- AC inverter drives
- UPS



Absolute Maximum Ratings $T_c = 25 ^{\circ}C$, unless otherwise specified					
Symbol	Conditions		Values	Units	
IGBT					
V _{CES}	T _j = 25 °C		1200	V	
I _C	T _j = 150 °C	T _{case} = 25 °C	150	Α	
		T _{case} = 80 °C	110	Α	
I _{CRM}	I _{CRM} =2xI _{Cnom}		200	Α	
V_{GES}			± 20	V	
t _{psc}	V_{CC} = 600 V; $V_{GE} \le 20$ V; $V_{CES} < 1200$ V	T _j = 125 °C	10	μs	
Inverse D	iode				
I _F	T _j = 150 °C	T _{case} = 25 °C	150	Α	
		T _{case} = 80 °C	100	Α	
I _{FRM}	I _{FRM} =2xI _{Fnom}		200	Α	
I _{FSM}	$t_p = 10 \text{ ms}; \sin.$	T _j = 150 °C	1100	Α	
Freewhee	ling Diode				
I _F	T _j = 150 °C	T_{case} = 25 °C	200	Α	
		T _{case} = 80 °C	135	Α	
I _{FRM}			300	Α	
I _{FSM}	t _p = 10 ms; sin.	T _j = 150 °C	1440	Α	
Module					
I _{t(RMS)}			500	Α	
T _{vj}			- 40 + 150	°C	
T _{stg}			-40 + 125	°C	
V _{isol}	AC, 1 min.		2500	V	

Characteristics $T_c = 25 ^{\circ}\text{C}$, unless otherwise specified						ecified
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 4 \text{ mA}$		4,5	5,5	6,5	V
I _{CES}	$V_{GE} = 0 V, V_{CE} = V_{CES}$	T _j = 25 °C		0,1	0,3	mA
		T _j = 125 °C				mA
V _{CE0}		T _j = 25 °C		1,4	1,6	V
		T _j = 125 °C		1,6	1,8	V
r _{CE}	V _{GE} = 15 V	T _j = 25°C		11	14	mΩ
		T _j = 125°C		15	19	$\text{m}\Omega$
V _{CE(sat)}	I _{Cnom} = 100 A, V _{GE} = 15 V	T _j = °C _{chiplev.}		2,5	3	V
C _{ies}				6,5	8,5	nF
C _{oes}	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		1	1,5	nF
C _{res}				0,5	0,6	nF
Q_G	V _{GE} = -8V - +20V			1000		nC
R _{Gint}	T _j = °C			2,5		Ω
t _{d(on)}				160	320	ns
t _r	R_{Gon} = 6,8 Ω	V _{CC} = 600V		80	160	ns
E _{on}		I _C = 100A		13		mJ
t _{d(off)}	$R_{Goff} = 6.8 \Omega$	T _j = 125 °C		400	520	ns
t _f		$V_{GE} = \pm 15V$		70	100	ns
E _{off}				11		mJ
R _{th(j-c)}	per IGBT				0,15	K/W



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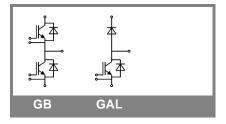
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Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Units
Inverse D	Diode					•
$V_F = V_{EC}$	I_{Fnom} = 100 A; V_{GE} = 0 V			2	2,5	V
		$T_j = 125 ^{\circ}C_{\text{chiplev.}}$ $T_j = 25 ^{\circ}C$		1,8		V
V_{F0}				1,1	1,2	V
		T _j = 125 °C				V
r _F		T _j = 25 °C		9	13	mΩ
		T _j = 125 °C				mΩ
I _{RRM}	I _F = 100 A	T _j = 125 °C		50		A
Q _{rr}	di/dt = 1000 A/µs			5		μC
E _{rr}	V _{GE} = 0 V; V _{CC} = 600 V					mJ
$R_{th(j-c)D}$	per diode				0,3	K/W
	eling Diode	ı				•
$V_F = V_{EC}$	I _{Fnom} = 150 A; V _{GE} = 0 V			2	2,5	V
		$T_j = 125 ^{\circ}C_{\text{chiplev.}}$ $T_j = 25 ^{\circ}C$		1,8		V
V_{F0}				1,1	1,2	V
		T _j = 125 °C				V
r _F		T _j = 25 °C		6	8,7	V
		T _j = 125 °C				V
I _{RRM}	I _F = 100 A	T _j = 25 °C		40 5		A
Q _{rr}	\/ -0\/:\/ -600\/			5		μC
E _{rr}	V _{GE} = 0 V; V _{CC} = 600 V					mJ
$R_{th(j-c)FD}$	per diode				0,25	K/W
Module	i.	ı				•
L _{CE}				15	20	nH
R _{CC'+EE'}	res., terminal-chip	T _{case} = 25 °C		0,35		mΩ
		T _{case} = 125 °C		0,5		mΩ
$R_{\text{th(c-s)}}$	per module				0,038	K/W
M _s	to heat sink M6		3		5	Nm
M _t	to terminals M6		2,5		5	Nm
w					325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.





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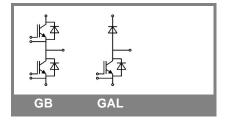
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Z _{th}						
Symbol	Conditions	Values	Units			
Z _{Ri}	i = 1	105	mk/W			
R_i	i = 2	35	mk/W			
R_i	i = 3	8	mk/W			
R_{i}	i = 4	2	mk/W			
tau _i	i = 1	0,03	s			
tau _i	i = 2	0,03	s			
tau _i	i = 3	0,0014	s			
tau _i	i = 4	0,0001	s			
Z R _i						
R _i	i = 1	210	mk/W			
R_i	i = 2	70	mk/W			
R_{i}	i = 3	16	mk/W			
R_{i}	i = 4	4	mk/W			
tau _i	i = 1	0,0623	s			
tau _i	i = 2	0,0083	s			
tau _i	i = 3	0,003	s			
tau _i	i = 4	0,0002	s			

